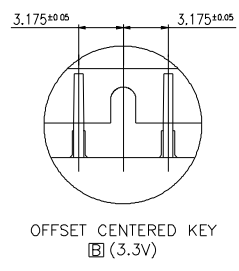
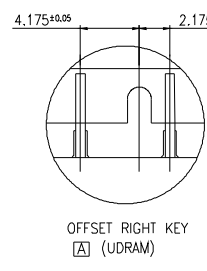
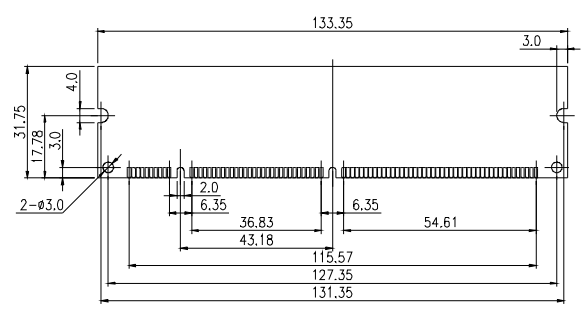
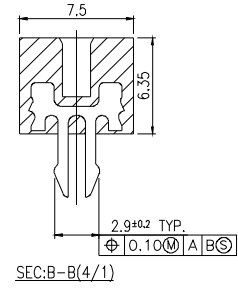
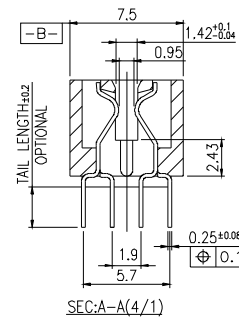
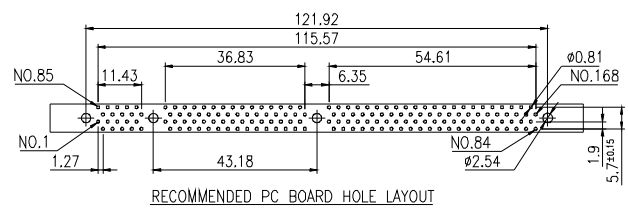
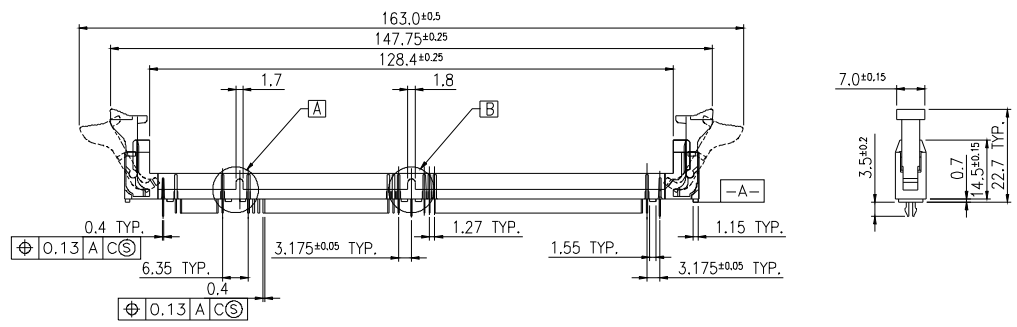
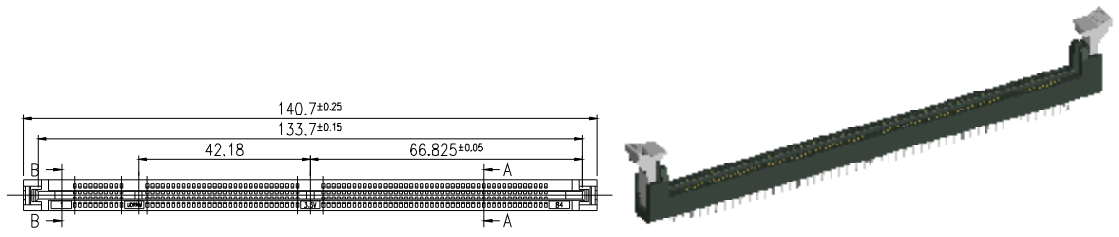


**DIMM SOCKET
CONNECTOR**

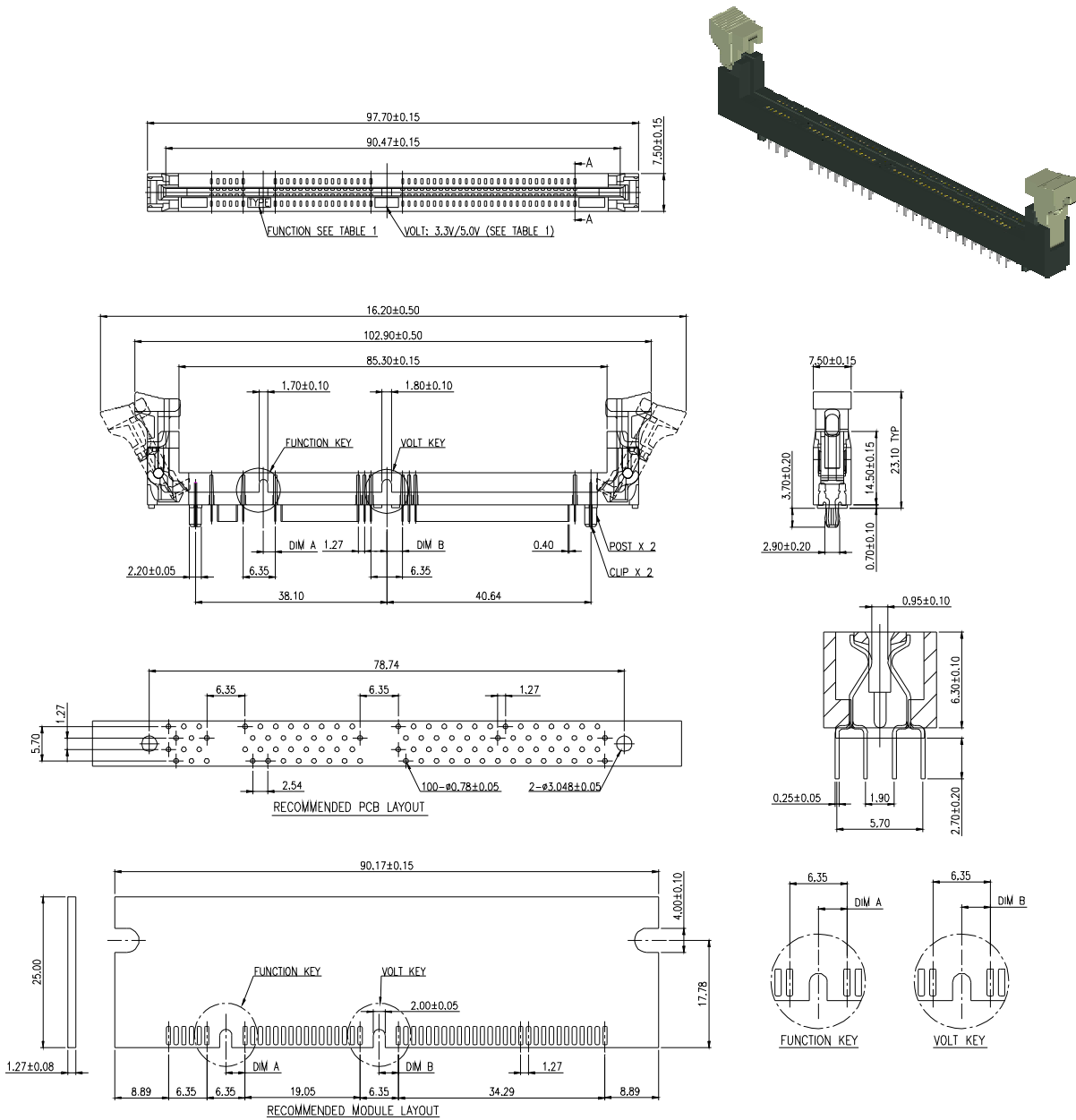
DIMM 1X3 SERIES STRAIGHT TYPE - P



| | | | | | | |
|---|------------|-------------------------------------|---------------------------|---|--------------------------------------|---|
| DIMM | 1X3 | P | 168 | GX | X | X |
| DIMM SOCKET | | PCB TYPE P: STRAIGHT TYPE | NO. OF PINS 168 | CONTACT PLATING OPTION GfT: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G30I: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL | VOLTAGE 3: 3.3V 5: 5.0V | HOUSING MATERIAL N: NYLON-66 (STANDARD) L: LCP P: PBT |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH X: TAIL LENGTH OPTIONS -0: 2.7mm -3: 3.0mm -4: 4.1mm 3: FUNCTION KEY, UDRAM(STANDARD) | | | | | | |

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 1X3 SERIES STRAIGHT TYPE - P

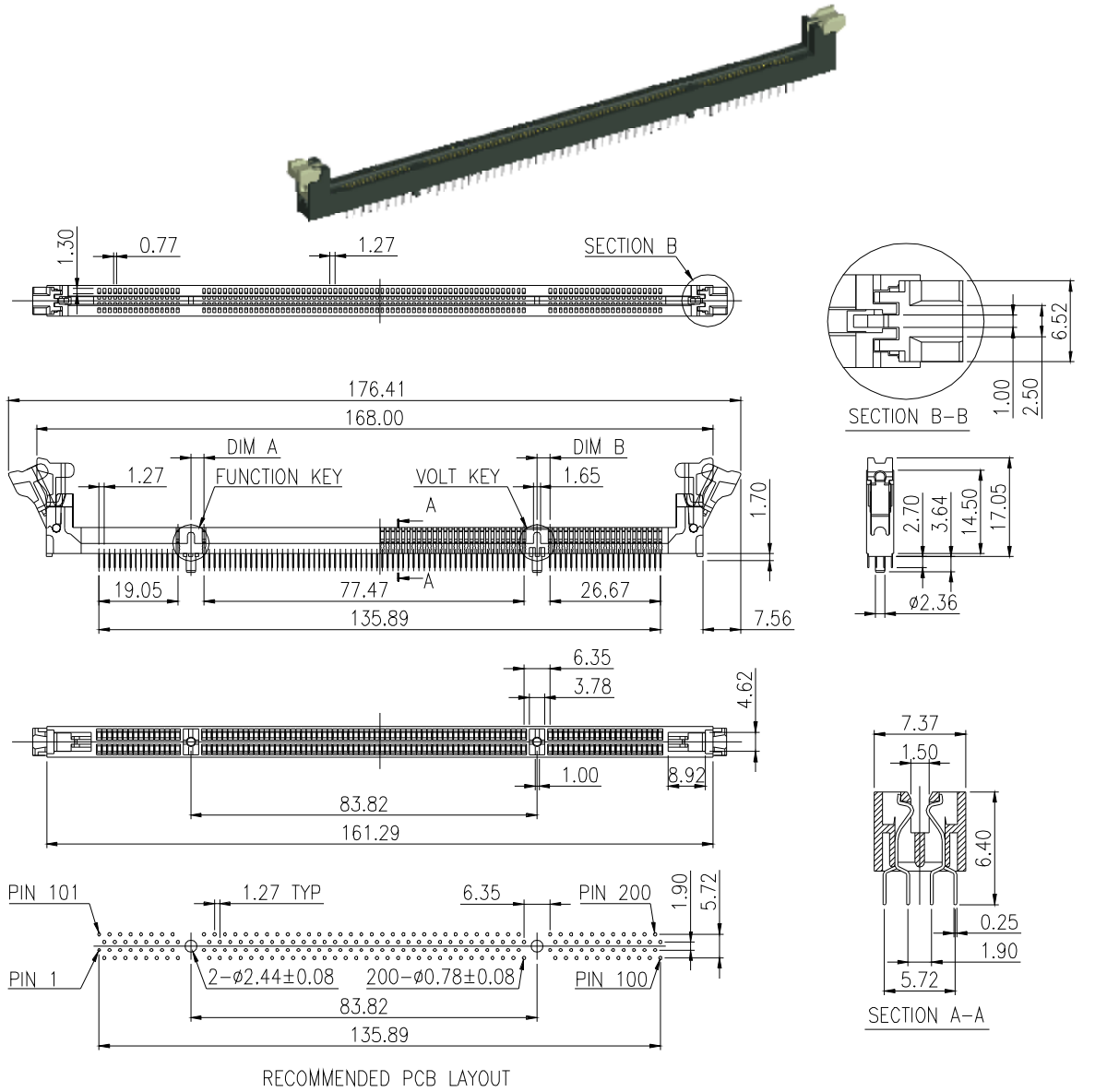


| MODULE KEY CONFIGURATION | DIM A | DIM B | MODULE KEY CONFIGURATION | DIM A | DIM B |
|-----------------------------------|-------|-------|-------------------------------------|-------|-------|
| STANDARD DRAM, 5 VOLT (DRAM) | 3.175 | 4.175 | STANDARD DRAM, 3.3 VOLT (DRAM) | 3.175 | 3.175 |
| SYNC.DRAM, 5 VOLT (SDRAM) | 4.175 | 4.175 | SYNC.DRAM, 3.3 VOLT (SDRAM) | 4.175 | 3.175 |
| NON-STANDARD DRAM, 5 VOLT (UDRAM) | 2.175 | 4.175 | NON-STANDARD DRAM, 3.3 VOLT (UDRAM) | 2.175 | 3.175 |

| | | | | | | |
|--|------------|-------------------------------------|---------------------------|--|---|--|
| DIMM | 10X | P | 100 | Gft | X | L |
| DIMM SOCKET | | PCB TYPE P: STRAIGHT TYPE | NO. OF PINS 100 | CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL | VOLTAGE 3: 3.3V (STANDARD) 5: 5.0V | HOUSING MATERIAL L: LCP (STANDARD) |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH 0X: FUNCTION KEY -01: SDRAM -02: DRAM -03: UDRAM (STANDARD) | | | | | | |

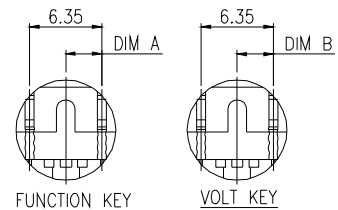
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 10X SERIES STRAIGHT TYPE - P



RECOMMENDED PCB LAYOUT

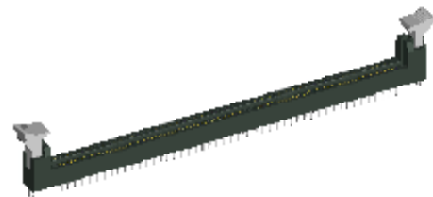
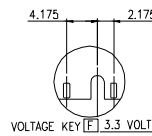
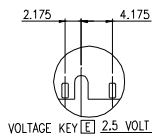
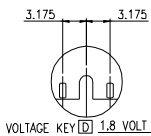
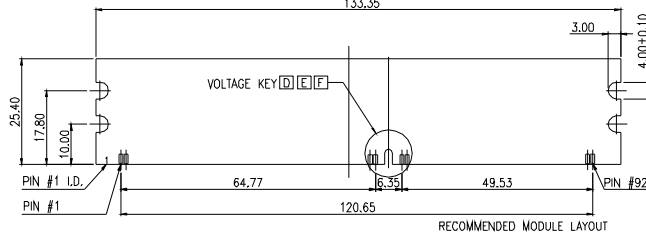
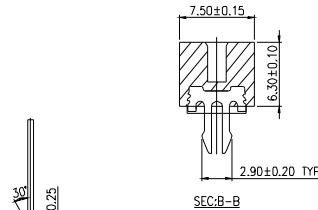
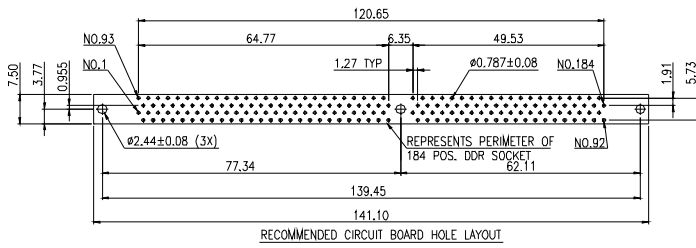
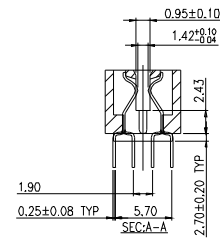
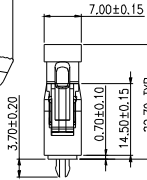
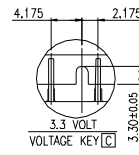
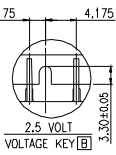
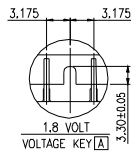
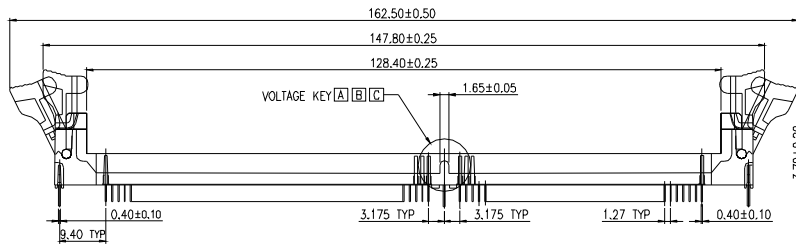
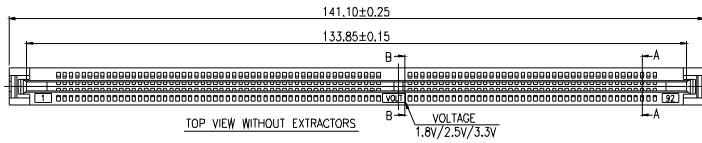
| MODULE KEY CONFIGURATION | DIM A | DIM B | MODULE KEY CONFIGURATION | DIM A | DIM B |
|-----------------------------------|-------|-------|-------------------------------------|-------|-------|
| STANDARD DRAM, 5 VOLT (DRAM) | 3.175 | 4.175 | STANDARD DRAM, 3.3 VOLT (DRAM) | 3.175 | 3.175 |
| SYNC.DRAM, 5 VOLT (SDRAM) | 4.175 | 4.175 | SYNC.DRAM, 3.3 VOLT (SDRAM) | 4.175 | 3.175 |
| NON-STANDARD DRAM, 5 VOLT (UDRAM) | 2.175 | 4.175 | NON-STANDARD DRAM, 3.3 VOLT (UDRAM) | 2.175 | 3.175 |



| | | | | | | | | | |
|-------------|---|---|------------------------------|--------------------|---|---|---|--|--|
| DIMM | 10X | - | P | 200 | - | Gft | - | X | X |
| DIMM SOCKET | SERIES NO. 1: LATCH TYPE, HIGH LATCH 0X: FUNCTION KEY -01: SDRAM -02: DRAM -03: UDRAM (STANDARD) | | PCB TYPE P: STRAIGHT TYPE | NO. OF PINS 200 | | CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL | | VOLTAGE 3: 3.3V (STANDARD) 5: 5.0V | HOUSING MATERIAL N: NYLON-66 (STANDARD) L: LCP P: PBT |

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

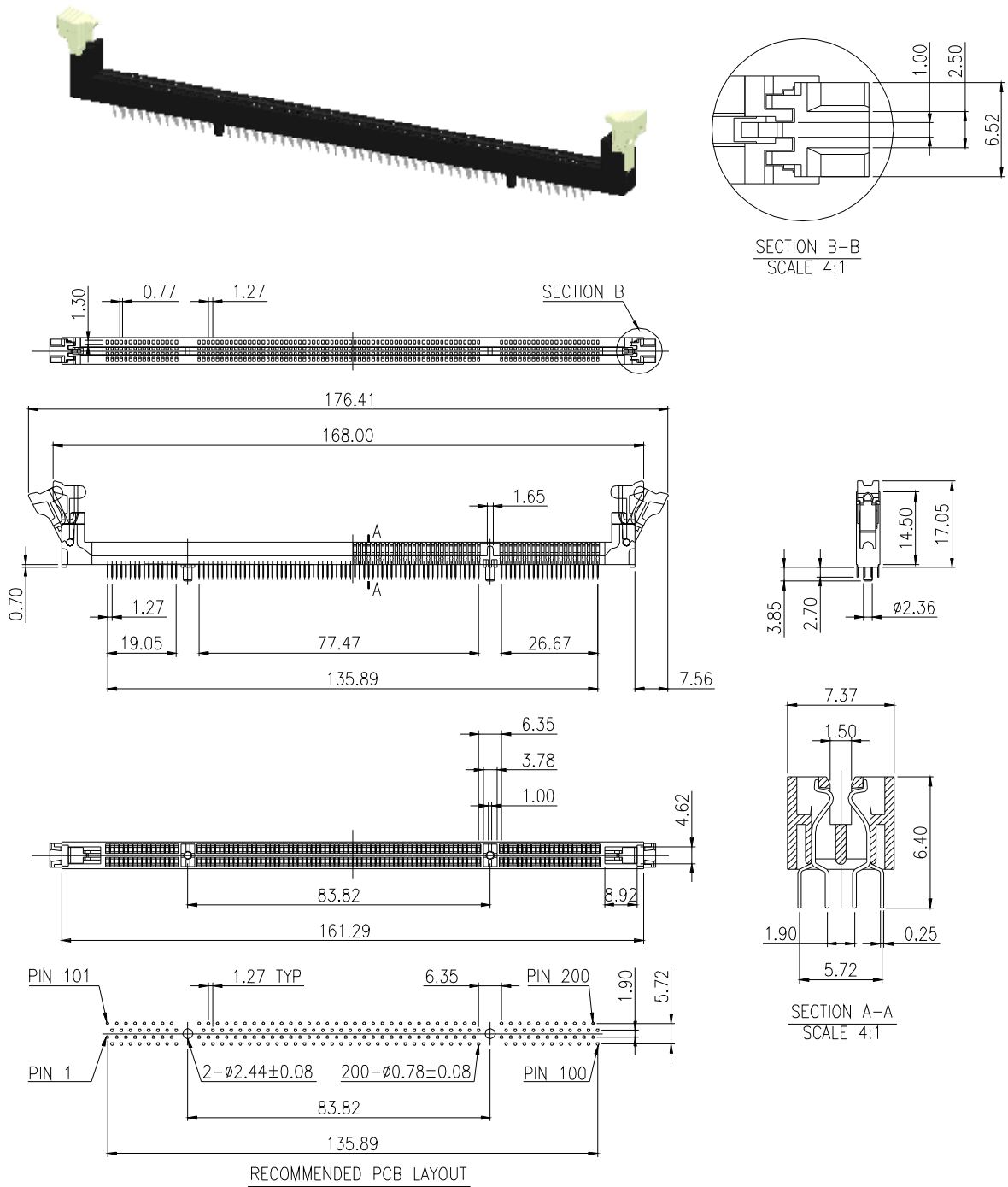
DIMM 104 SERIES STRAIGHT TYPE - P



| | | | | | | |
|--------------------|---|-------------------------------------|---------------------------|--|---|---|
| DIMM | 104 | P | 184 | Gft | X | X |
| DIMM SOCKET | SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | PCB TYPE P: STRAIGHT TYPE | NO. OF PINS 184 | CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL | VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V | HOUSING MATERIAL N: NYLON 66 (STANDARD) L: LCP |

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

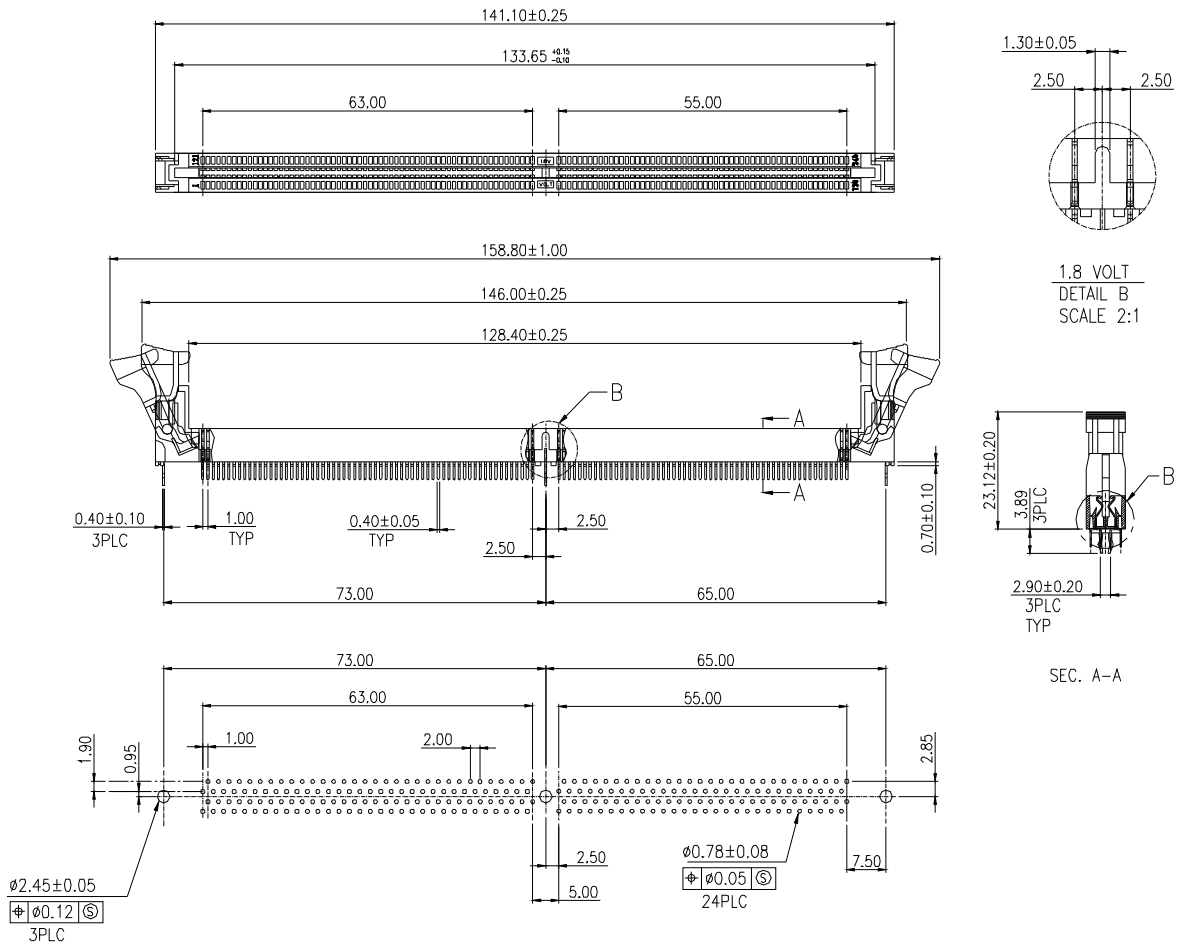
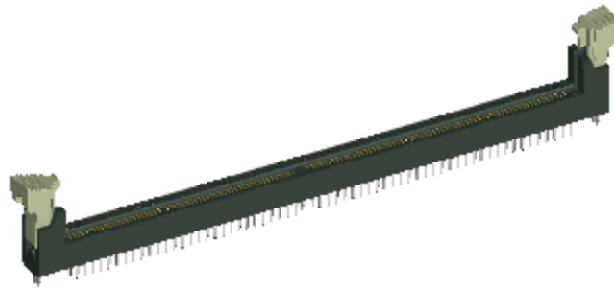
DIMM 104 SERIES STRAIGHT TYPE - P



| | | | | | | |
|--------------------|---|-------------------------------------|---------------------------|--|--------------------------------------|---|
| DIMM | 104 | P | 200 | Gft | X | X |
| DIMM SOCKET | SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | PCB TYPE P: STRAIGHT TYPE | NO. OF PINS 200 | CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL | VOLTAGE 1: 1.8V 2: 2.5V | HOUSING MATERIAL N: NYLON 66 (STANDARD) L: LCP P: PBT |

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

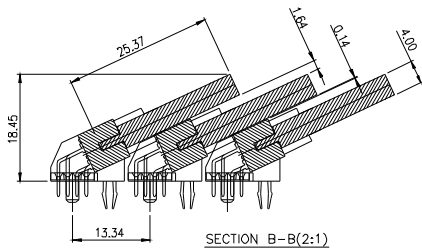
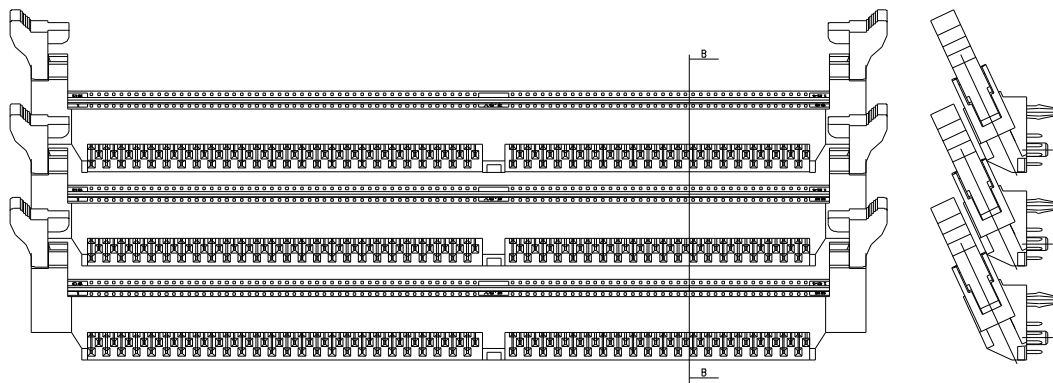
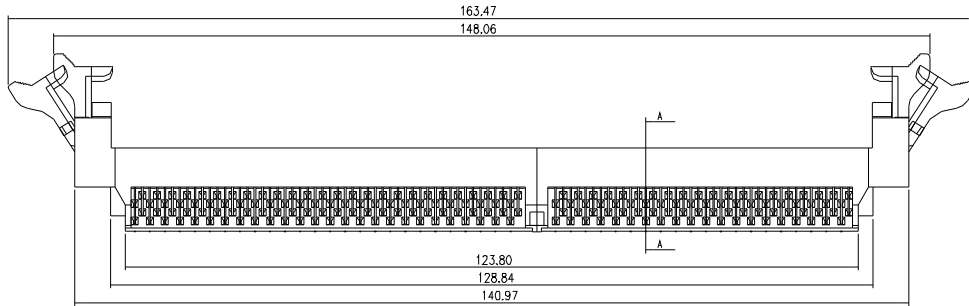
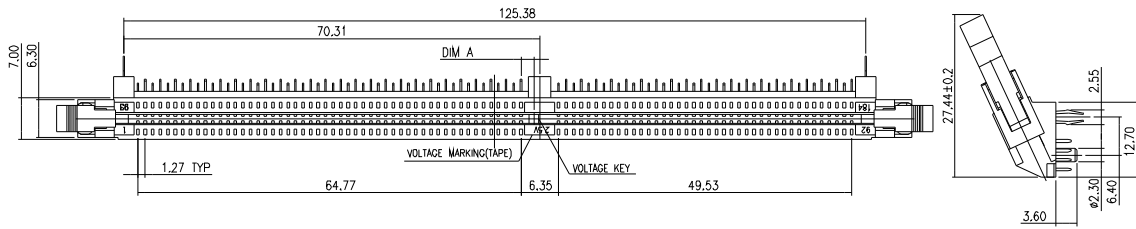
DIMM 104 SERIES STRAIGHT TYPE - P



| | | | | | | | |
|---|------------|--|---------------------------|-----------|---|----------|---|
| DIMM | 104 | P | 240 | GX | X | X | X |
| DIMM SOCKET | | PCB TYPE P: STRAIGHT TYPE | NO. OF PINS 240 | | VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V | | COLOR TYPE 0: WHITE 1: BLACK |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | | CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL | | | HOUSING MATERIAL N: NYLON 66 (STANDARD) | | |

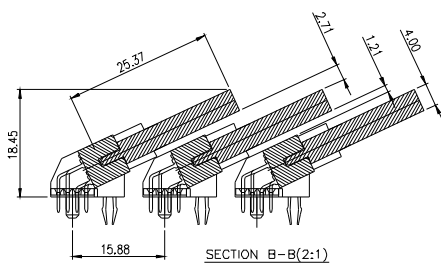
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr



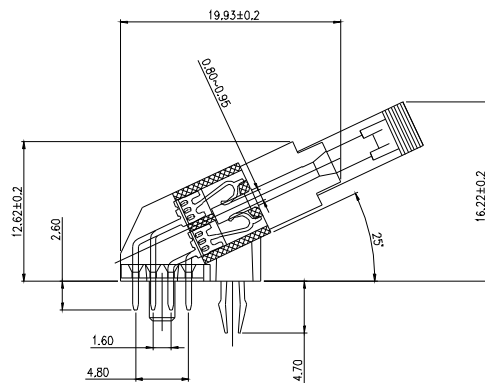
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

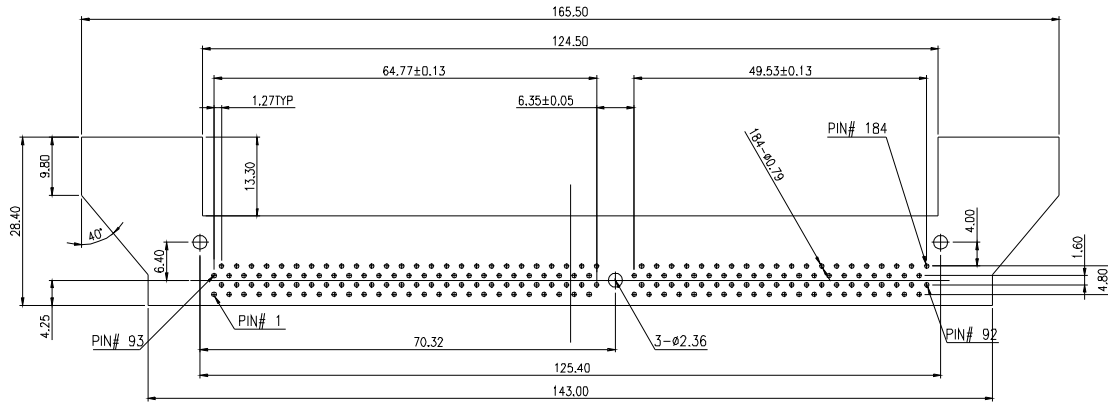
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



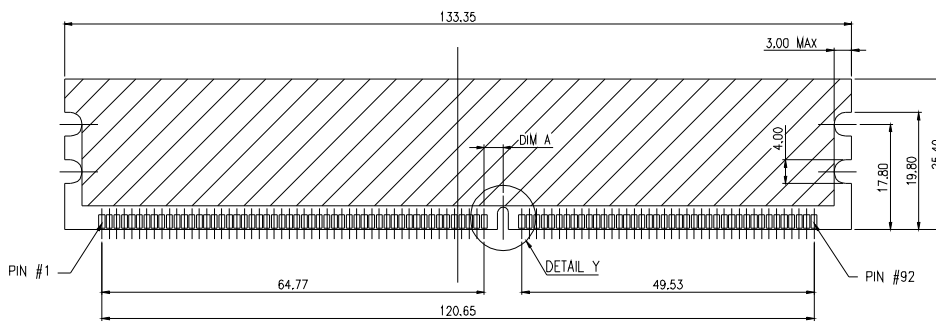
SECTION A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

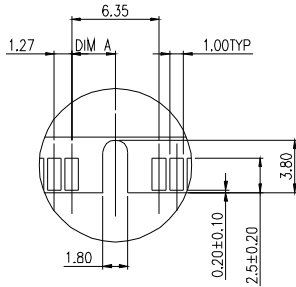
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr



P.C. BOARD HOLE LAYOUT

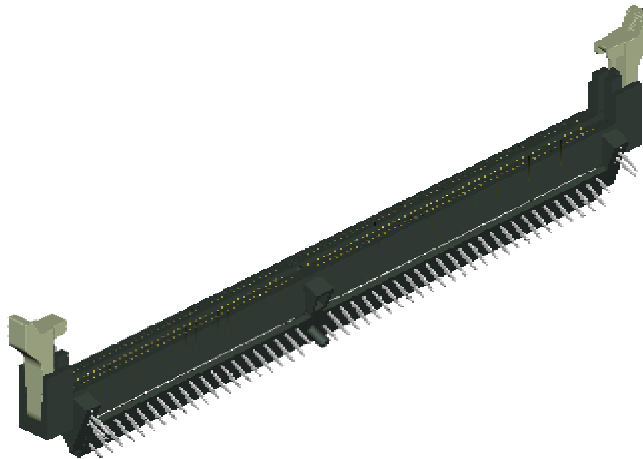


DAUGHTER CARD REQUIREMENT



DETAIL Y
SCALE 2:1

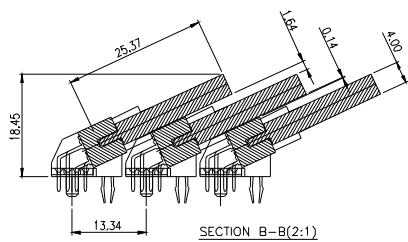
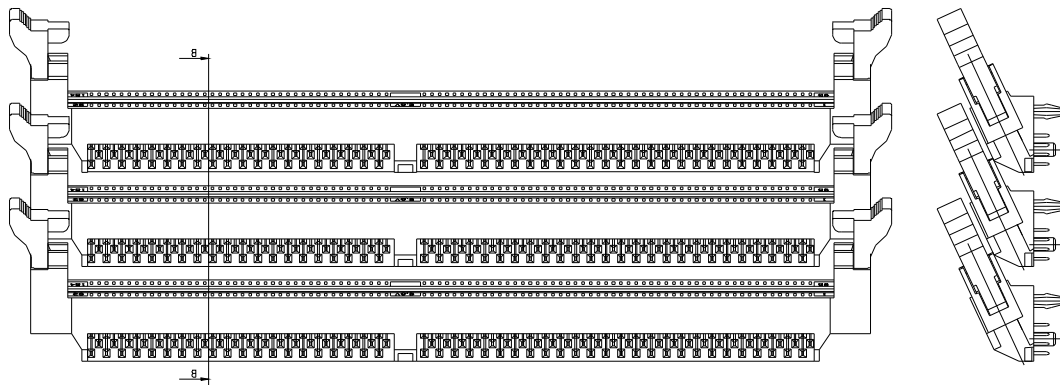
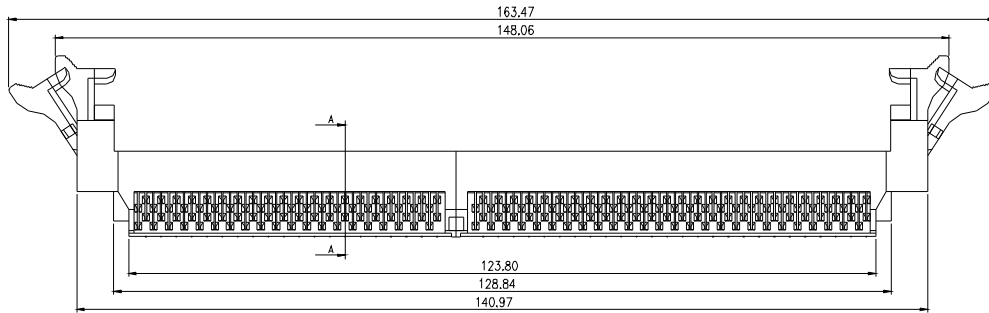
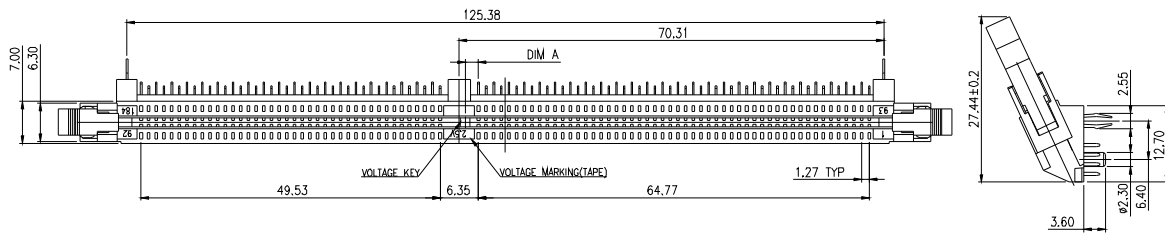
| VOLTAGE | DIM A |
|---------|-------|
| 1.8V | 3.175 |
| 2.5V | 2.175 |
| 3.3V | 4.175 |



| | | | | | | |
|--|------------|---|---------------------------|-----------|---|-----------------------------------|
| DIMM | 104 | Pr | 184 | GX | X | L |
| DIMM SOCKET | | PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE | NO. OF PINS 184 | | VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V | HOUSING MATERIAL L: LCP |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | | | | | | |
| CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL | | | | | | |

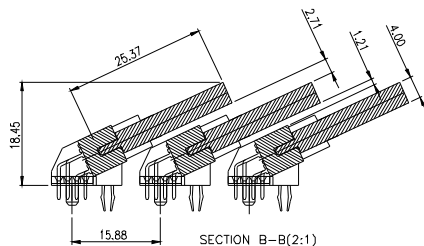
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



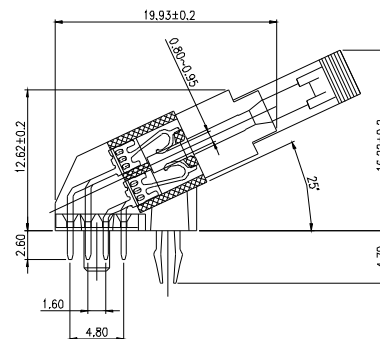
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

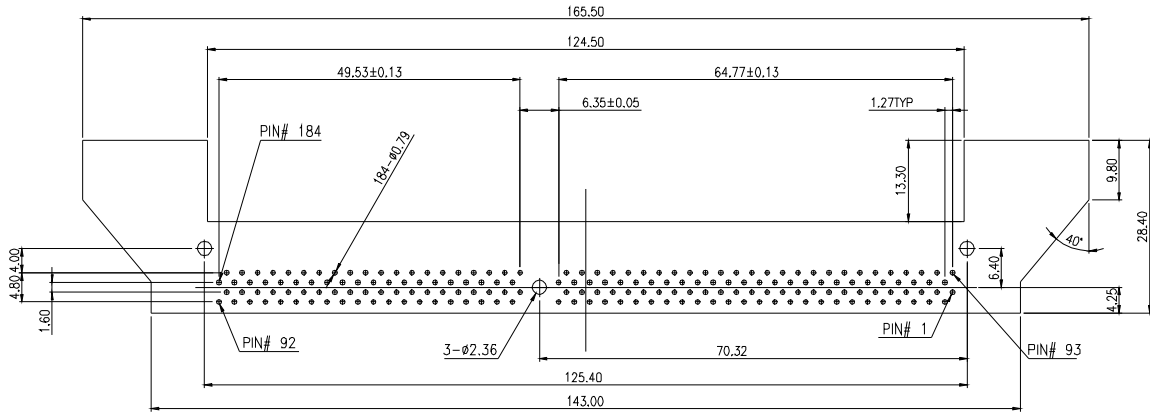
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



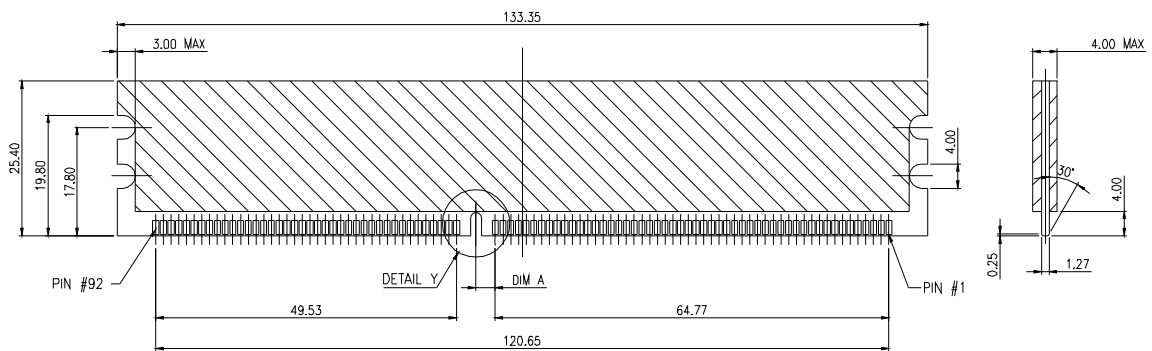
SECTION A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

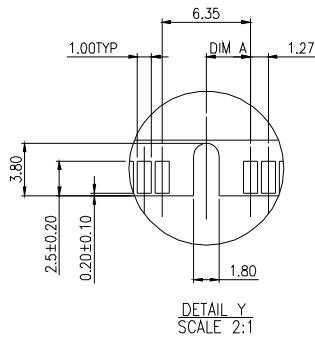
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



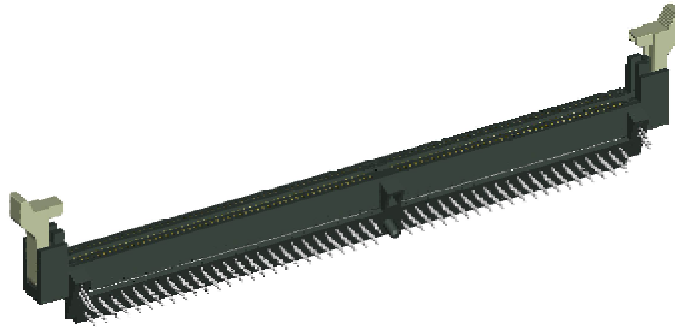
P.C. BOARD HOLE LAYOUT



DAUGHTER CARD REQUIREMENTS



DETAIL Y
SCALE 2:1

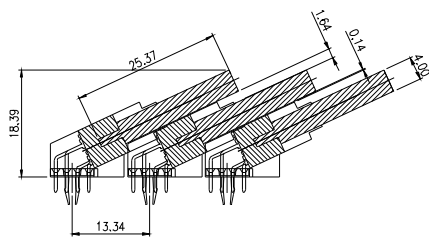
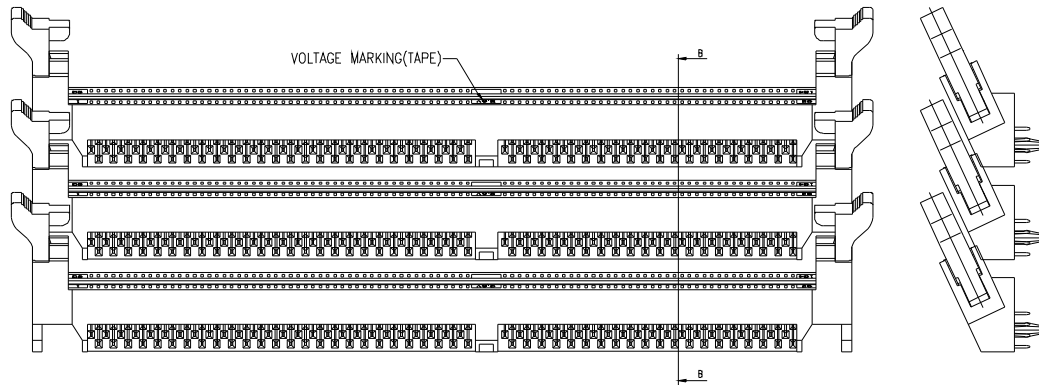
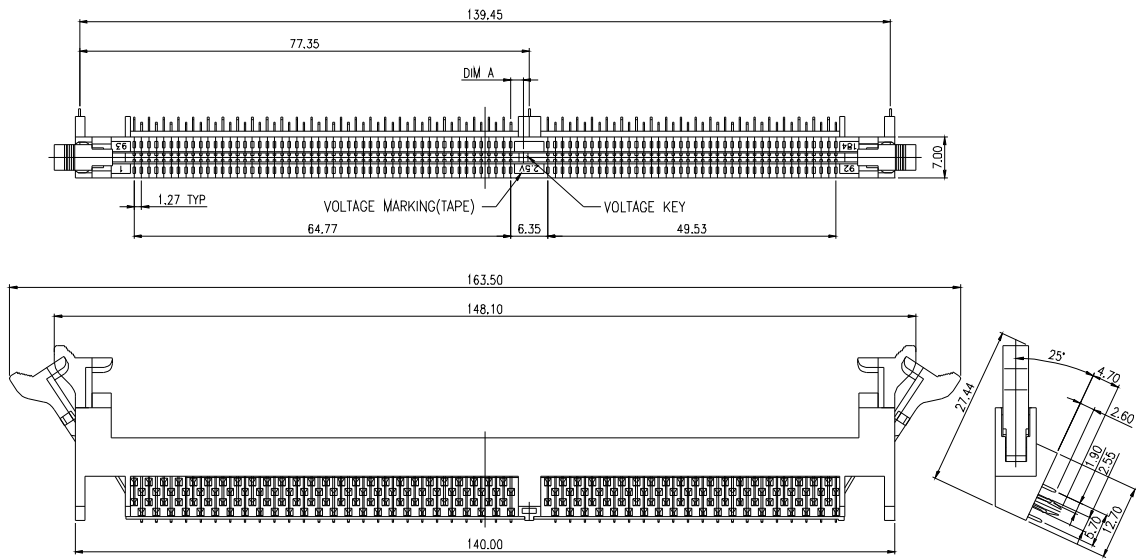


| VOLTAGE | DIM A |
|---------|-------|
| 1.8V | 3.175 |
| 2.5V | 2.175 |
| 3.3V | 4.175 |

| | | | | | | | |
|---|------------|--|---------------------------|-----------|---|----------|---------------------------------------|
| DIMM | 104 | Pr | 184 | GX | X | L | R |
| DIMM SOCKET | | PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE | NO. OF PINS 184 | | VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V | | INSERT TYPE R: REVERSE TYPE |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | | CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL | | | HOUSING MATERIAL L: LCP | | |

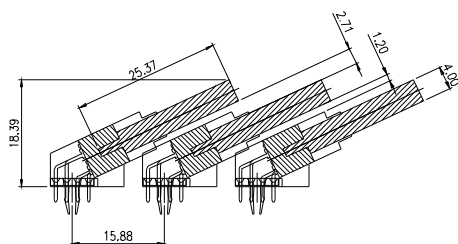
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr



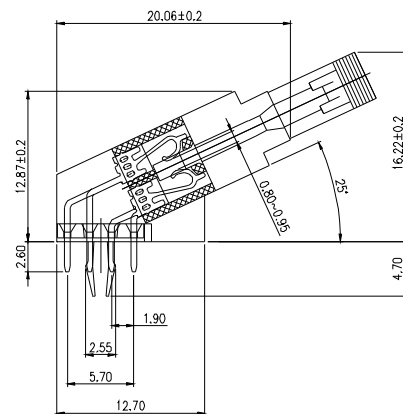
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

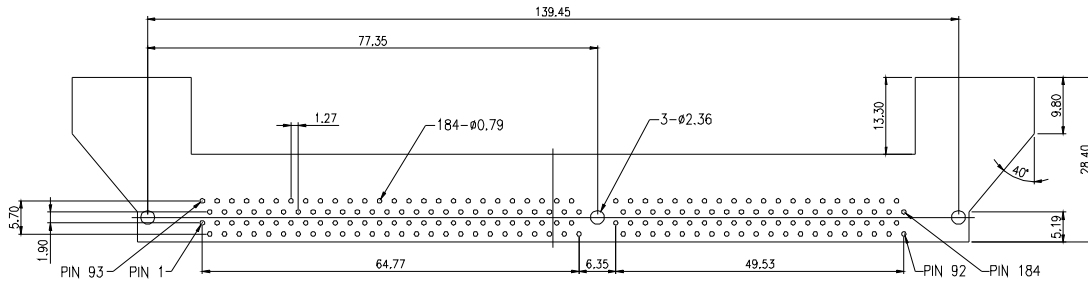
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



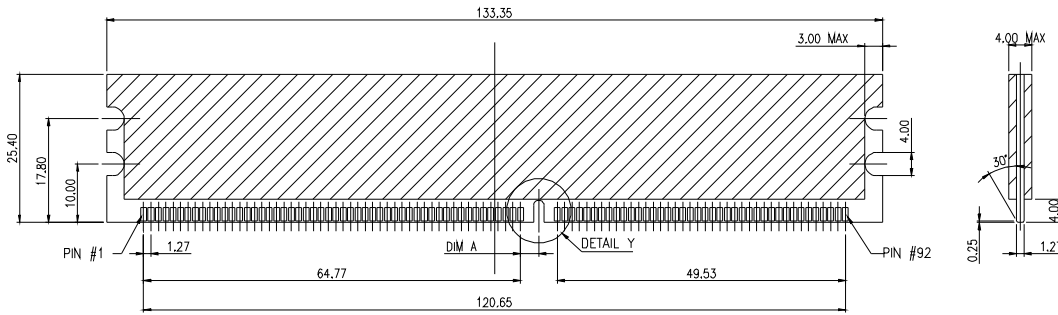
SECT A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

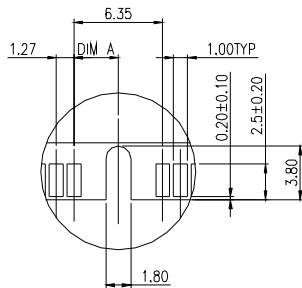
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



P.C. BOARD HOLE LAYOUT

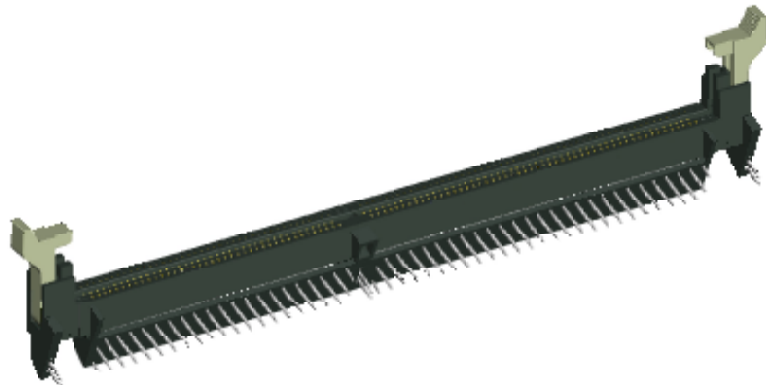


DAUGHTER CARD REQUIREMENTS



DETAIL Y
SCALE 2:1

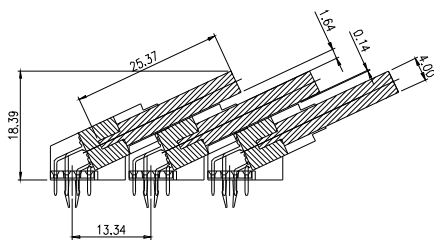
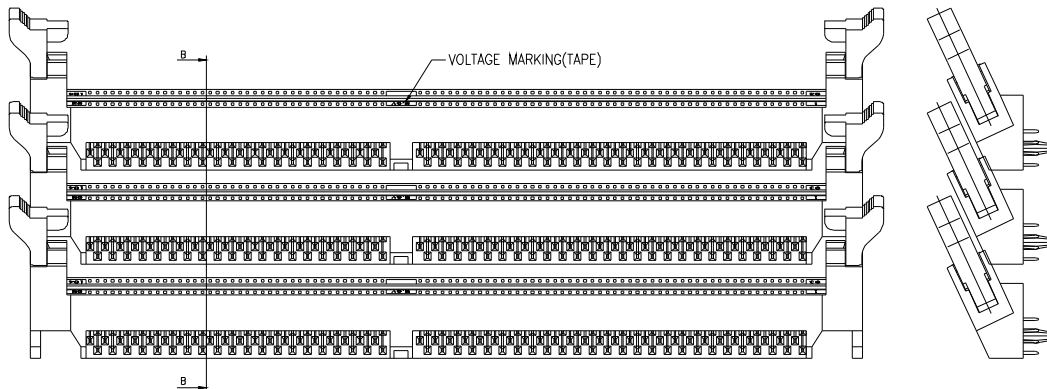
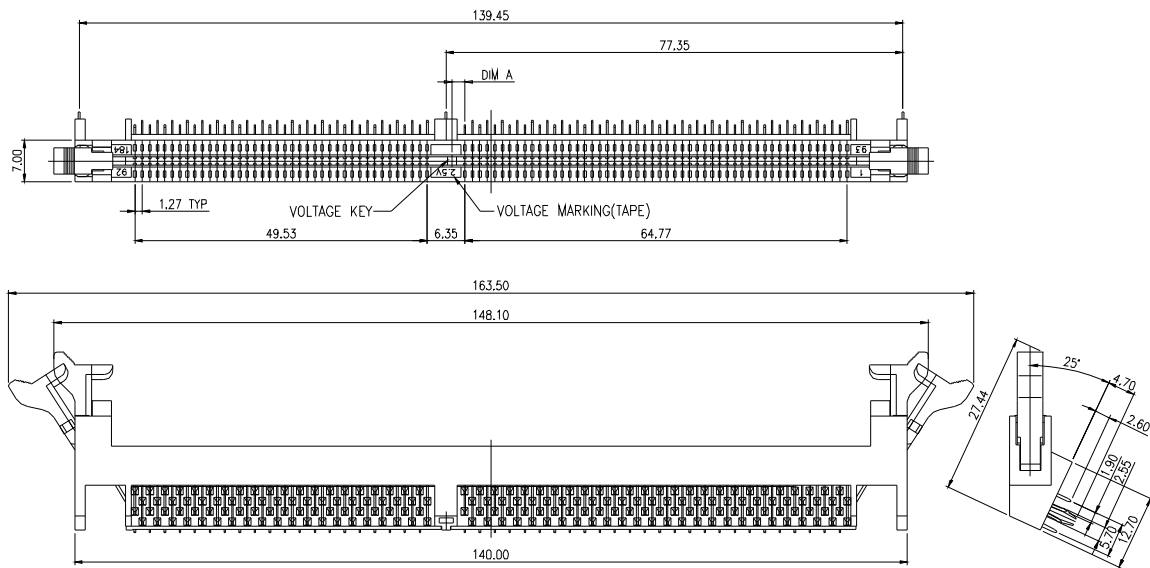
| VOLTAGE | DIM A |
|---------|-------|
| 1.8V | 3.175 |
| 2.5V | 2.175 |
| 3.3V | 4.175 |



| | | | | | | | |
|---|------------|--|---------------------------|-----------|---|----------|---------------------------------|
| DIMM | 104 | Pr | 184 | GX | X | L | 9 |
| DIMM SOCKET | | PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE | NO. OF PINS 184 | | VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V | | ROW SPACING 9: 1.90mm |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | | CONTACT PLATING OPTION Gf: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL | | | HOUSING MATERIAL L: LCP | | |

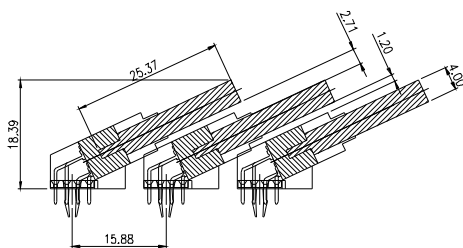
NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



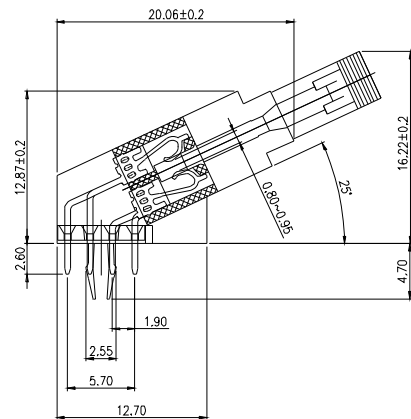
SECTION B-B(2:1)

MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 WILL LEAVE APPROXIMATELY 0.14 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



SECTION B-B(2:1)

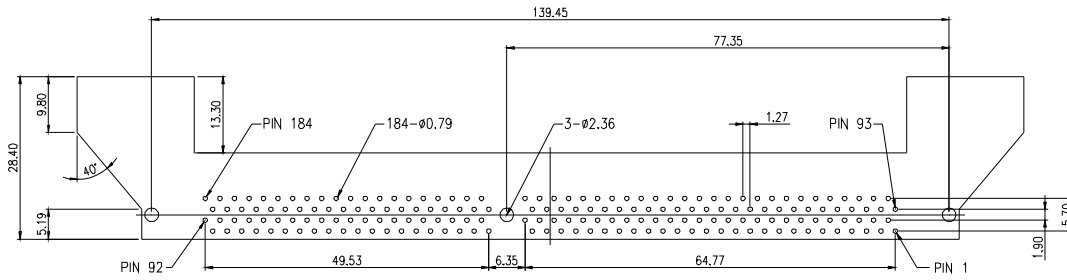
MINIMUM SOCKET TO SOCKET SPACING
 WITH A 4.00 WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 15.88 WILL LEAVE APPROXIMATELY 1.21 OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



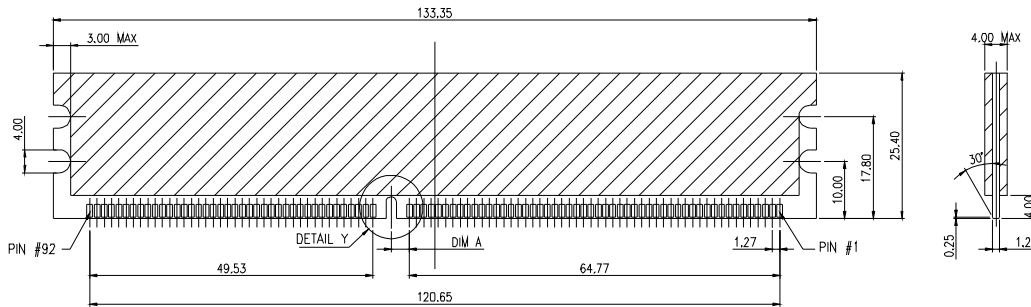
SECT A-A(2:1)

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE

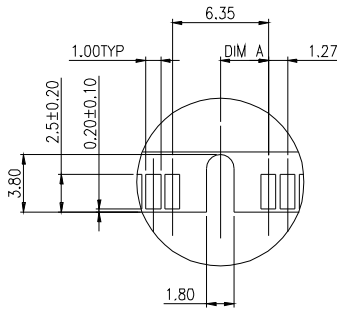
DIMM 104 SERIES RIGHT ANGLE 25 DEGREE TYPE - Pr(REVERSE TYPE)



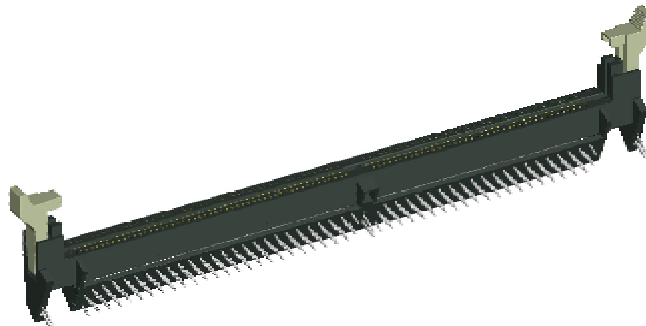
P.C. BOARD HOLE LAYOUT



DAUGHTER CARD REQUIREMENTS



DETAIL Y
SCALE 2:1



| VOLTAGE | DIM A |
|---------|-------|
| 1.8V | 3.175 |
| 2.5V | 2.175 |
| 3.3V | 4.175 |

| | | | | | | | | |
|---|------------|---|---------------------------|-----------------------------------|---|----------|---------------------------------------|---------------------------------|
| DIMM | 104 | Pr | 184 | GX | X | L | R | 9 |
| DIMM SOCKET | | PCB TYPE Pr: RIGHT ANGLE 25 DEGREE TYPE | NO. OF PINS 184 | | VOLTAGE 1: 1.8V 2: 2.5V 3: 3.3V | | INSERT TYPE R: REVERSE TYPE | |
| SERIES NO. 1: LATCH TYPE, HIGH LATCH 04: DDR RAM | | CONTACT PLATING OPTION Gft: GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL G15t: 15u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL G30t: 30u" GOLD ON CONTACT, TIN PLATING ON SOLDER TAIL | | | | | | ROW SPACING 9: 1.90mm |
| | | | | HOUSING MATERIAL L: LCP | | | | |

NOTE : SOME SIZES, STYLES AND OPTION ARE NON-STANDARD, NON-CANCELLABLE, NON-RETURNABLE